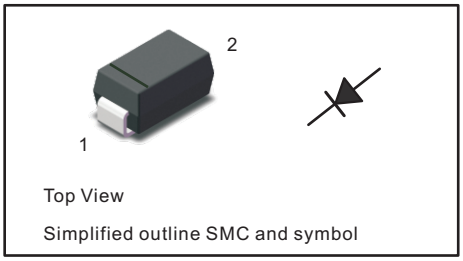
8.0Amp Surface mount fast recovery rectifiers

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 260℃/10 seconds at terminals

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View

Simplified outline SMC and symbol

Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.008 ounce, 0.225 grams

Marking



Product Name,X : A.B.....M

Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	RS8AC	RS8BC	RS8DC	RS8GC	RS8JC	RS8KC	RS8MC	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T_L=100℃	$I_{(AV)}$	8.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	175.0							A
Maximum instantaneous forward voltage at 8.0A	V_F	1.30							V
Maximum DC reverse current T_A=25℃ at rated DC blocking voltage T_A=125℃	I_R	2.0 200							uA
Maxinum reverse recovery time(Note 1)	Trr	150				250	500		ns
Typical junction capacitance (Note2)	C_J	70.0							pF
Typical thermal resistance	R_{qJA}	47.0							°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150							°C

Note: 1.Reverse recovery time test condition: IF=0.5A IR=1.0A Irr=0.25A

2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

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Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

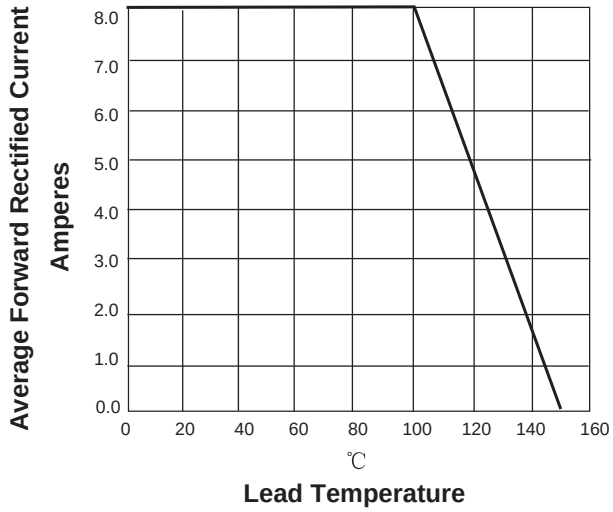


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

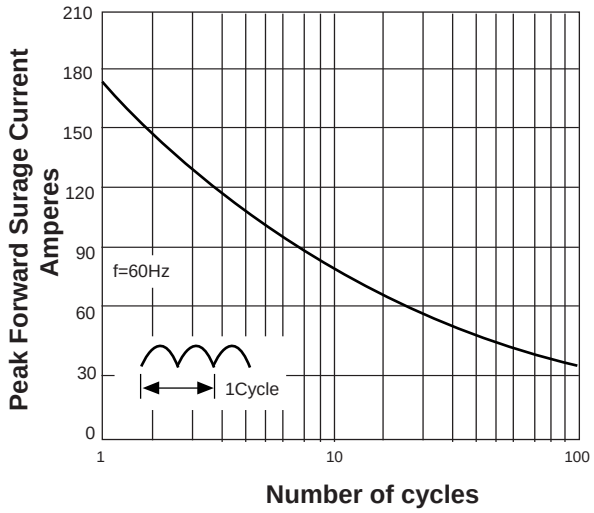


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

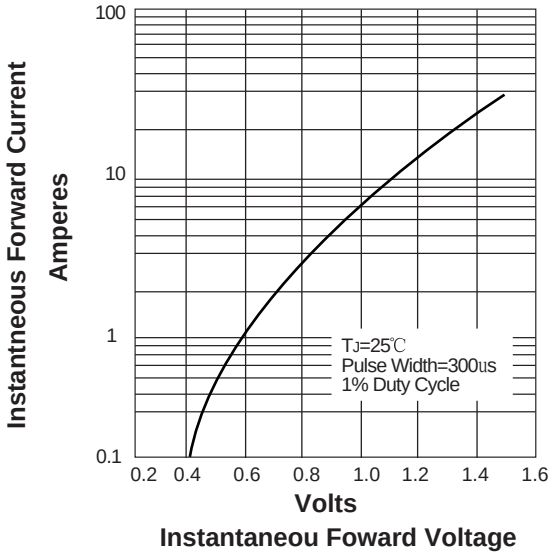
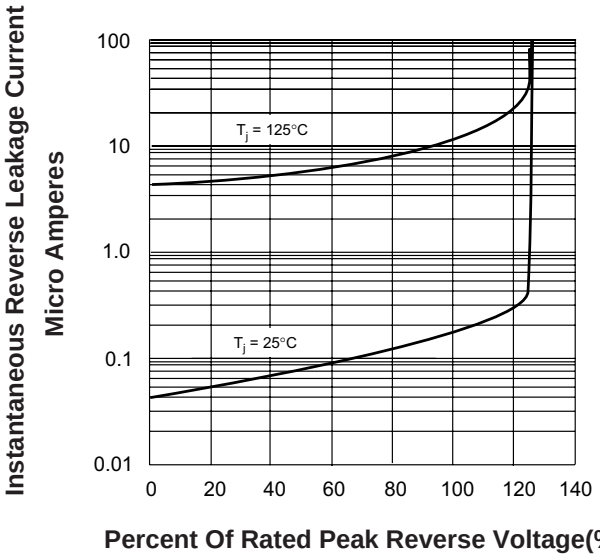
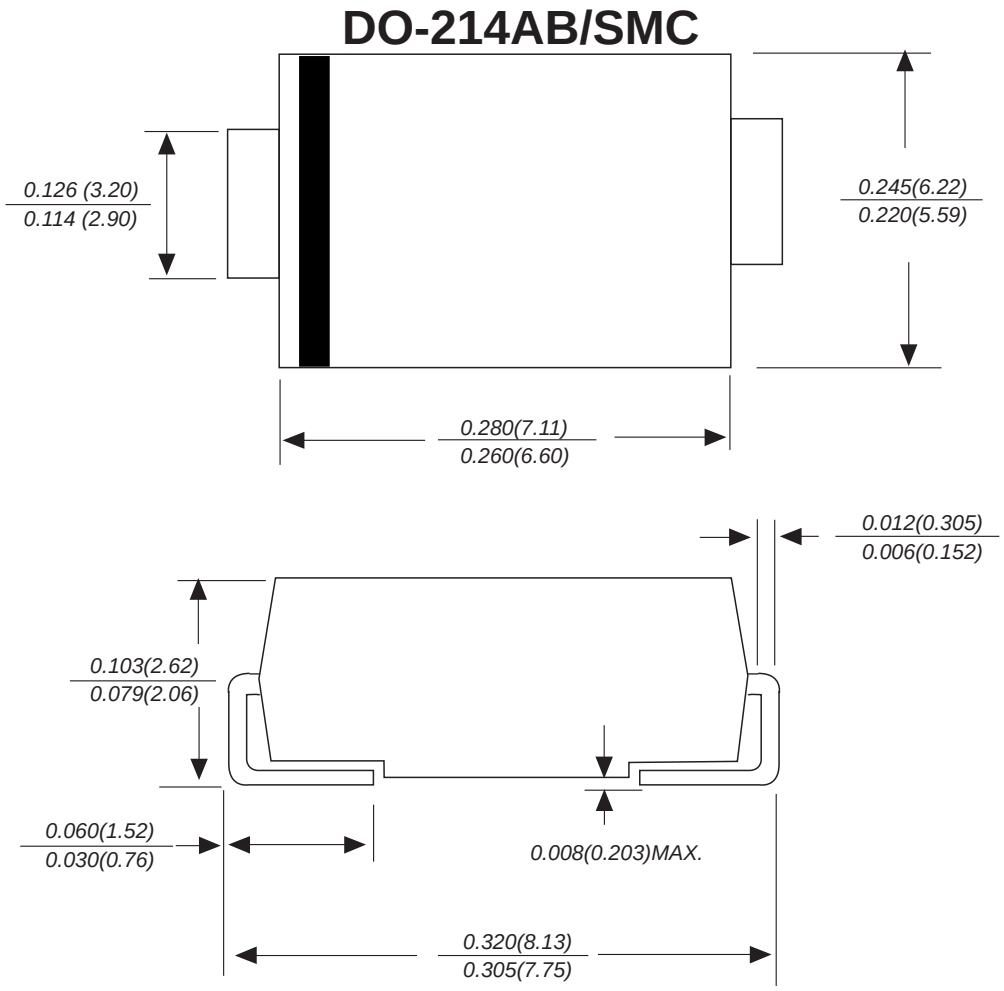


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

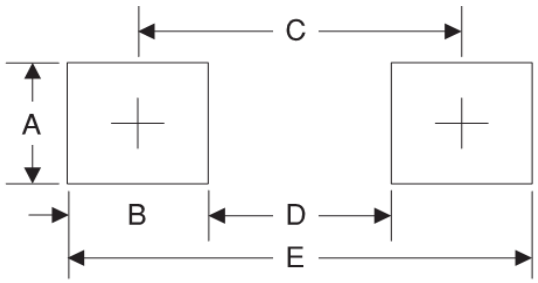


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Dimensions in inches and (millimeters)



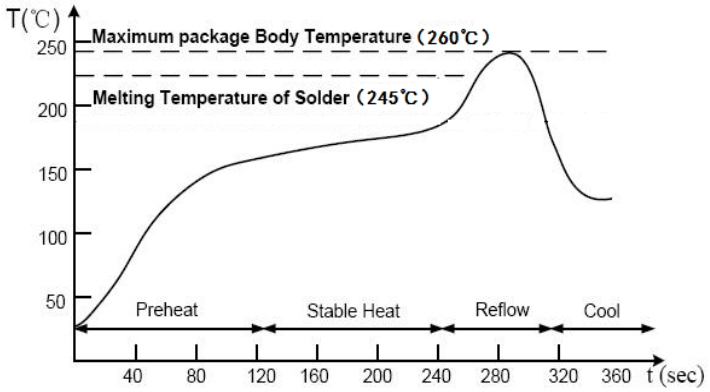
Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
B	2.50	0.098
C	6.80	0.268
D	4.40	0.173
E	9.40	0.370

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Suggested Soldering Temperature Profile

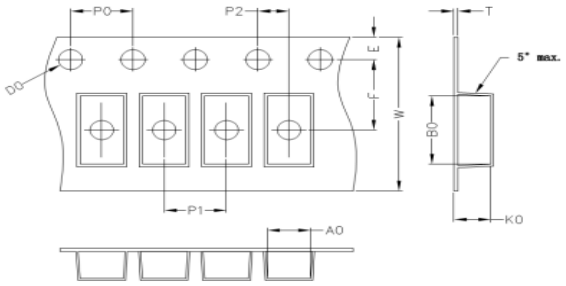


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
6.05	8.31	2.54	1.55	1.75	7.50
P0	**P1**	**P2**	**T**	**W**	**Tolerance**
4.0	8.0	2.0	0.25	16	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMC	13'	330	3.0	340	6.0	360*360*360	48